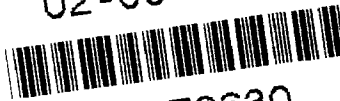


02-06-2006



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DOCKET NUMBER: SC14687HP

To the Honorable Commissioner of Patents and Trademarks, please record the attached original documents or copy thereof.

## 1. Name of conveying party(ies):

Hei Ming SHIU  
On Lok CHAU  
Gor Amie LAI

Additional name(s) of conveying party(ies) attached?

☐

Yes

☒

No

## 3 Name of conveyance:

☒

Assignment

☐

Merger

☐

Security Agreement

☐

Change of Name

☐

Other

Execution Date: 3 January, 2006.

## 2. Name and address of receiving party(ies)

Name: FREESCALE SEMICONDUCTOR, INC.Internal Address: Law DepartmentStreet Address: 7700 West Parmer LaneCity: AustinState: TXZip: 78729

Additional name(s) &amp; address(es) attached?

☐

Yes

☒

No

## 4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is 3 January, 2006.

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached?

☐

Yes

☒

No

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: FREESCALE SEMICONDUCTOR, INC.

Internal Address:

MD: TX32/PL02

Street Address:

7700 West Parmer LaneCity: AustinState: TXZip: 78729

## 6. Total number of applications and patents involved:

1

## 7. Total fee (37 CFR 3.41)

\$40.00☐

Enclosed

☒

Authorized to be charged to deposit account

8. Deposit account number: 503079, Freescale Semiconductor, Inc.

(Attach duplicate copy of this page if paying by deposit account.)

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## 9 Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a

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Charles E. Bergere

Name of Person Signing

Signature

Date

Total number of pages including cover sheet, attachments, and documents:

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SC14687HP

PATENT  
REEL: 017506 FRAME: 0855

## PATENT ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, we, **Hei Ming SHIU, On Lok CHAU and Gor Amie LAI, all of Hong Kong**, have sold, assigned and transferred, and do hereby sell, assign and transfer, unto FREESCALE SEMICONDUCTOR, INC., a corporation of the State of Delaware, having its principal office in Austin, Texas, United States of America, and its successors, assigns, and legal representatives, the entire right, title and interest for the United States of America in and to certain inventions relating to improvements in **METHOD FOR FORMING MULTI-LAYER BUMPS ON A SUBSTRATE** (Docket No. SC14687HP), described, illustrated and claimed in an application for Letters Patent of the United States of America executed by us on the dates indicated by our signatures below, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any division, extension, continuation or reissue thereof.

We hereby also sell, assign and transfer unto FREESCALE SEMICONDUCTOR, INC., the entire right, title and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the invention and the applications for Letters Patent in foreign countries, and we further authorize FREESCALE SEMICONDUCTOR, INC. to apply for Letters Patent in foreign countries directly in its own name, and to claim priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation or reissue, to FREESCALE SEMICONDUCTOR, INC., for the sole use and benefit of FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives, to the full end of the term for which Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to FREESCALE SEMICONDUCTOR, INC.

We agree that, when requested, we will, without charge to FREESCALE SEMICONDUCTOR, INC., but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives or nominees.

We covenant with FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.

Hei Ming SHIU  
Hei Ming SHIU

DATE: 03 JAN 2006

Lee Kwong Cheung  
WITNESS LEE KWONG CHEUNG

DATE: 03 JAN 2006

Lee Kwong Cheung  
WITNESS

DATE: 03 JAN 2006

On Lok CHAU  
On Lok CHAU

DATE: 03 JAN 2006

Lee Kwong Cheung  
WITNESS LEE KWONG CHEUNG

DATE: 03 JAN 2006

Lee Kwong Cheung  
WITNESS

DATE: 03 JAN 2006

Gor Amie LAI  
Gor Amie LAI

DATE: 03 JAN 2006

Lee Kwong Cheung  
WITNESS LEE KWONG CHEUNG

DATE: 03 JAN 2006

Lee Kwong Cheung  
WITNESS

DATE: 03 JAN 2006